

Amendments to the Specification:

Please replace the paragraph at page 8, on line 31, with the following paragraph:

-- ~~Brief Description of the Intelligent designs~~ Brief Description of the Drawings--

Please replace the paragraph at page 9, from line 9 through line 10, with the following paragraph:

-- FIG. 3 shows a block diagram of one embodiment of the architecture of the inventive apparatus. FIG. 3A and FIG. 3B show multi platform execution where the client/server means that the invention modules interact among two or more networked computers.--

Please replace the paragraph at page 9, on line 11, with the following paragraph:

-- FIG. 4 shows a flow diagram of one embodiment of the inventive method. FIG. 4A and FIG. 4B show the tool process flow.--

Please add the following new paragraphs at page 9, between lines 13 and 15:

-- Advantages of the invention can be best understood in the context of electronic product hardware packaging and design phases. All electronic products can be divided into four levels of hardware packaging, as seen in Figure 2.

- IC Die (silicon by itself)
- IC Package (die in an enclosure)
- PCB (ICs on a board)
- System (PCBs in an enclosure) --